

# RKZ6.2KL

## Silicon Planar Zener Diode for Surge Absorption

REJ03G1253-0100

Rev.1.00

Nov 16, 2005

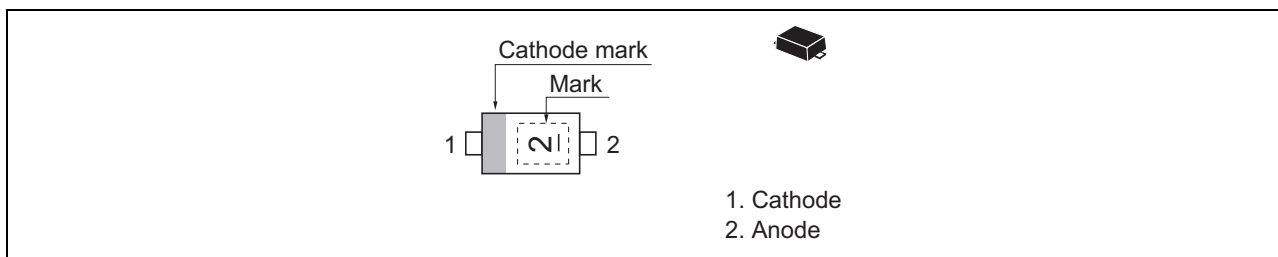
### Features

- IEC61000-4-2 Contact discharge : 30kV
- Extremely small Flat Lead Package (EFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKZ6.2KL	2	EFP	PXSF0002ZA-A (EFP)

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: See Fig.2.

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	Vz	5.86	—	6.53	V	Iz = 5 mA, 40 ms pulse
Reverse current	IR	—	—	2	μA	VR = 3.0 V
Dynamic resistance	rd	—	—	50	Ω	Iz = 5 mA
ESD-Capability *1	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both Forward and reverse direction 10 pulse

Notes: 1. Failure criterion ; IR &gt; 2 μA at VR = 3.0 V.

2. Please do not use the soldering iron due to avoid high stress.

3. For EFP Package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic

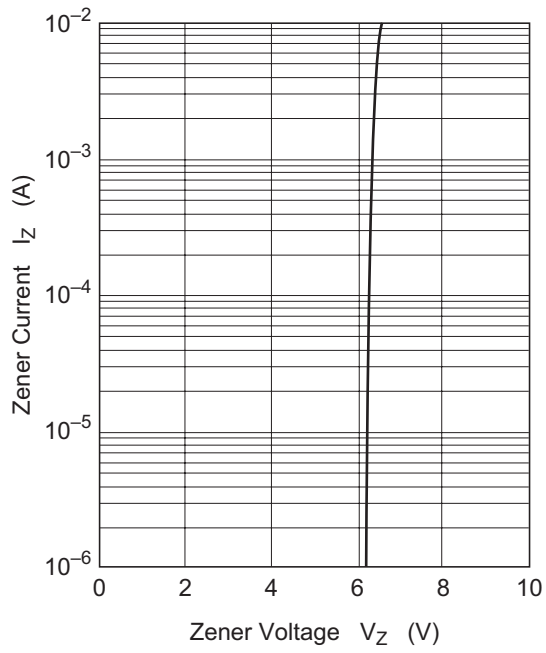


Fig.1 Zener current vs. Zener voltage

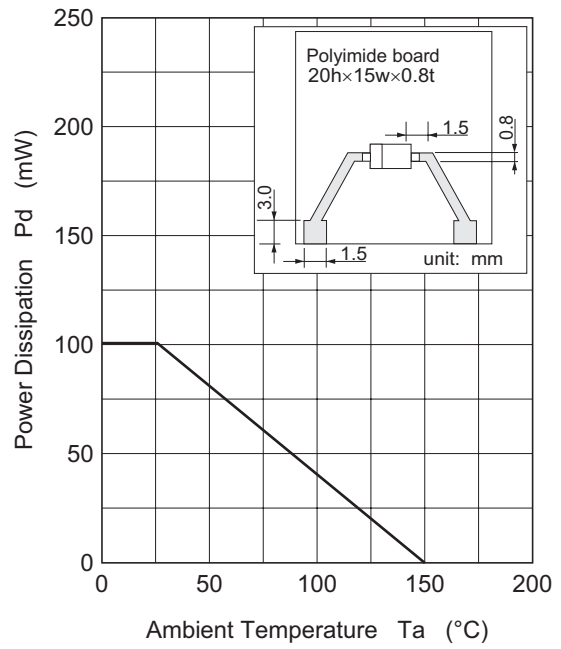


Fig.2 Power Dissipation vs. Ambient Temperature

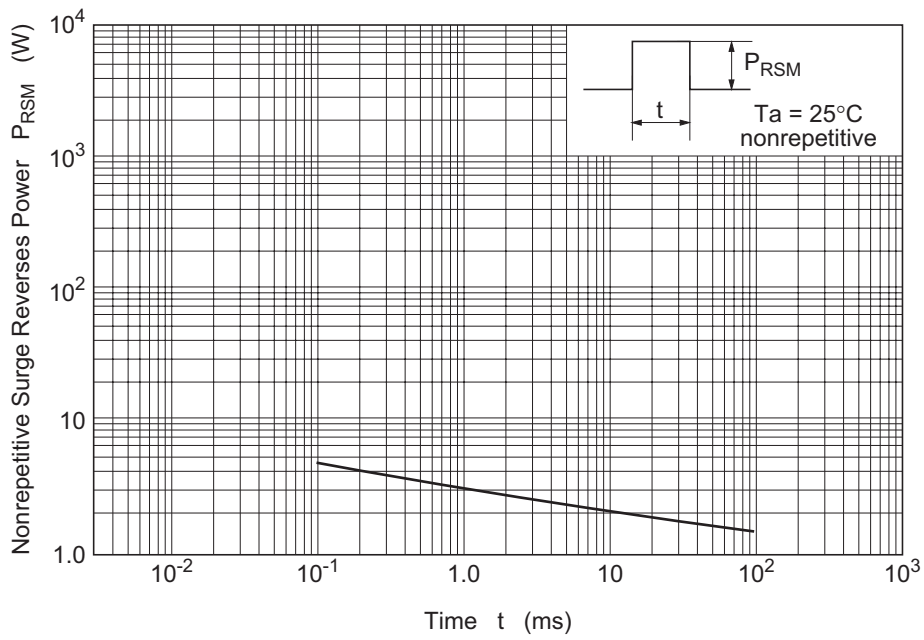
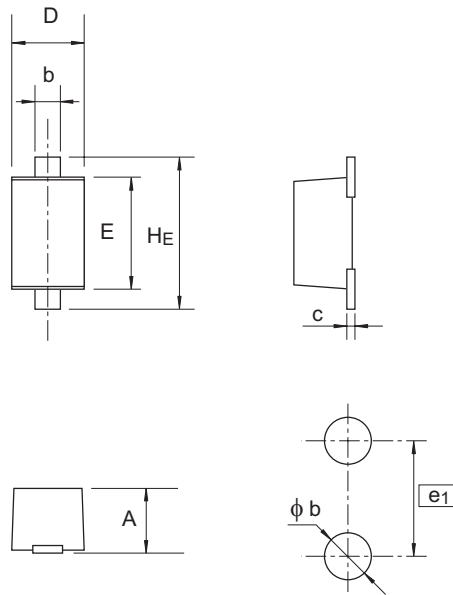


Fig.3 Surge Reverse Power Ratings

## Package Dimensions

Package Name EFP	JEITA Package Code —	RENESAS Code PXSF0002ZA-A	Previous Code EFP / EFPV	MASS[Typ.] 0.0007g
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Pattern of terminal position areas

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
A	0.44	0.47	0.50
b	0.25	0.30	0.35
c	0.08	0.13	0.18
D	0.55	0.60	0.65
E	0.75	0.80	0.85
$H_E$	0.95	1.00	1.05
$\phi b$	—	0.40	—
$e_1$	—	1.00	—

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